

| | Type | L # | Hits | Search Text | DBs |
|----|------|-----|-------|--|----------------------------|
| 1 | BRS | L5 | 603 | 257/737.ccls. | USPAT |
| 2 | BRS | L6 | 444 | 257/780.ccls. | USPAT |
| 3 | BRS | L7 | 1 | 5656863.pn. | USPAT |
| 4 | BRS | L8 | 1 | 5925931.pn. | USPAT |
| 5 | BRS | L9 | 48146 | CSP and (ball or bump) and solder | USPAT |
| 6 | BRS | L10 | 48073 | (chip adj size adj package) and (ball or bump) and solder | USPAT |
| 7 | BRS | L11 | 8403 | (chip adj size adj package) and (ball or bump) and solder and metal and pad | USPAT |
| 8 | BRS | L12 | 98 | (chip adj size adj package) and (ball or bump) and solder and metal and pad | USPAT |
| 9 | BRS | L13 | 12 | (chip adj size adj package) and (ball or bump) and solder and metal and pad and micron | USPAT |
| 10 | BRS | L14 | 43 | 257/737.ccls. and CSP | USPAT |
| 11 | BRS | L15 | 0 | 257/737.ccls. and CSP and microbump | USPAT |
| 12 | BRS | L16 | 4 | 257/737.ccls. and CSP and micron | USPAT |
| 13 | BRS | L17 | 6 | 257/737.ccls. and microbump | USPAT |
| 14 | BRS | L19 | 230 | 257/737.ccls. | EPO; JPO; IBM TDB |
| 15 | BRS | L21 | 98 | 257/780.ccls. | EPO; JPO; IBM TDB |
| 16 | BRS | L20 | 1 | (chip adj size adj package) and (ball or bump) and solder and metal and pad | EPO; JPO; IBM TDB |
| 17 | BRS | L18 | 75 | L12 and via | USPAT |